

AN 1995:374769 HCAPLUS
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 TI **Silver**-containing tin-base **solder**
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 SO Jpn. Kokai Tokkyo Koho, 5 pp.
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 DT Patent
 LA Japanese

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PI	JP 06269983	A2	19940927	JP 1993-58545	19930318
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AB	A solder contains Ag 5-20, Sn 70-90, Cu 0.05-10, Pd 0.05-2, and Fe , Co , and/or Ni 0.05-1%. The solder has high corrosion resistance and elec. and thermal cond. and is suitable for elec. industry.				